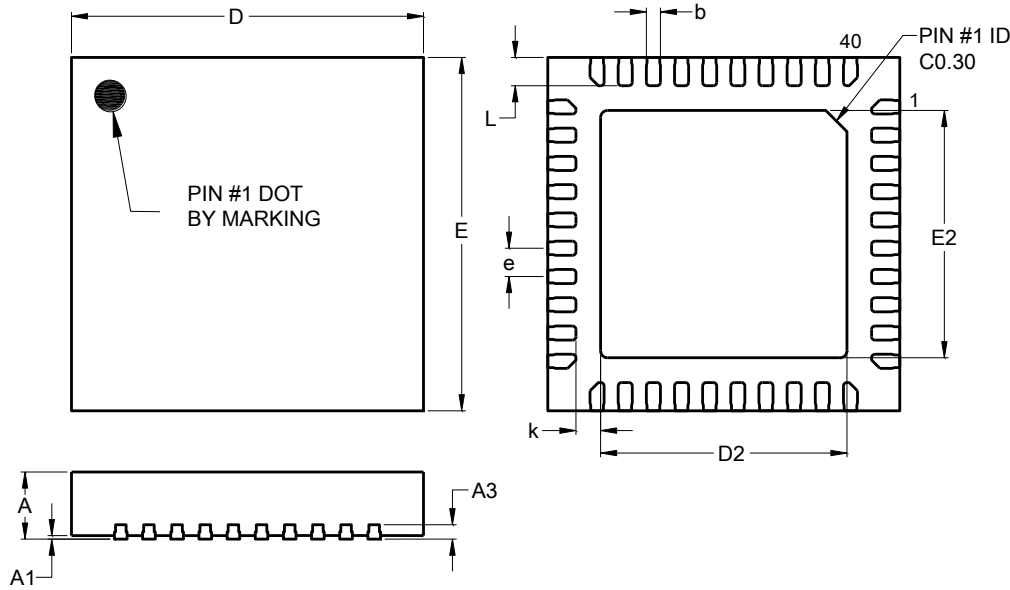


**Package Outline Dimensions**

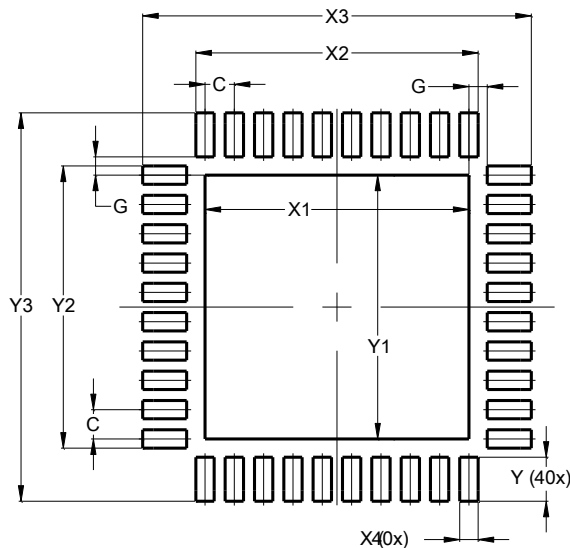
W-QFN5050-40 (Type US)



W-QFN5050-40 (Type US)			
Dim	Min	Max	Typ
A	0.700	0.800	0.750
A1	--	0.050	--
A3	0.203 REF		
b	0.150	0.250	0.200
D	4.950	5.050	5.000
D2	3.450	3.550	3.500
E	4.950	5.050	5.000
E2	3.450	3.550	3.500
e	0.400 BSC		
k	0.350 REF		
L	0.350	0.450	0.400
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

W-QFN5050-40 (Type US)



Dimensions	Value (in mm)
C	0.400
G	0.250
X	0.250
X1	3.600
X2	3.850
X3	5.300
Y	0.600
Y1	3.600
Y2	3.850
Y3	5.300

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.